

## DA1453x/DA1458x SDK

This document contains the release notes for Renesas DA14533/DA14535/DA14531-0x/DA14585/DA14586 Software Development Kit, version 6.0.24.1464.

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## 1. Terms and Definitions

API	Application Programming Interface
Bluetooth LE	Bluetooth® Low Energy
GA	General access
LA	Limited access
PER	Packet Error Rate
SDK	Software Development Kit
SUOTA	Software Update Over The Air
TRNG	True Random Number Generator

## 2. Release Data

Table 1. Release data

Device Number	Software Development Kit (SDK)
Device Type	DA145xx
Device Revision	DA14533, DA14535, DA14531-00, DA14531-01, DA14585, DA14586
Operating System	N/A
Operating System Version	N/A
Software Release Date	May 9, 2025
Software Version Number	6.0.24.1464
Software Release Type ( <a href="#">Note 1</a> )	FULL (GA)

**Note 1** Releases can be of the following types: FULL (GA), FULL (LA), RELEASE CANDIDATE, ENGINEERING, PATCH or BINARY

## 3. License

Licenses covering this SDK release are listed in the license.txt file in the SDK doc folder.

## 4. Related Documentation and References

- [1] UM-B-117, [DA14531 Getting Started Guide](#), User Manual, Renesas Electronics.
- [2] UM-B-165, [DA14535 Getting Started Guide](#), User Manual, Renesas Electronics.
- [3] R19US0026EE0100, [DA14533 Getting Started Guide](#), Manual, Renesas Electronics
- [4] UM-B-118, [SDK6 System Features and Peripheral Overview](#), Renesas Electronics.
- [5] UM-B-119, [DA14585/DA14531 SW Platform Reference Manual](#), Renesas Electronics.

**Note 1** References are for the latest published version, unless otherwise indicated.

## 5. Release Description

### 5.1 Overview

This is a GA release of SDK6 that runs on the DA14533, DA14535, DA14531-0x and DA14585/6 devices. This release can be used for application development.

### 5.2 New and Updated Features of 6.0.24.1464

Table 2. 6.0.24.1464 new features

Feature number	Description
1464_001	Added application files for profiles: <ul style="list-style-type: none"> <li>▪ Blood Pressure Profile (BLP)</li> <li>▪ Health Thermometer Profile (HTP)</li> <li>▪ Time Profile (TIP)</li> <li>▪ Heart Rate Profile (HRP)</li> <li>▪ Running Speed and Cadence Profile (RSCP)</li> <li>▪ HID Over Gatt Profile Device (HOGPD)</li> <li>▪ Phone Alert Status Profile (PASP)</li> <li>▪ Location and Navigation Profile (LANP)</li> <li>▪ Cycling Speed and Cadence Profile (CSCP)</li> <li>▪ Scan Parameters Profile (SCPP)</li> <li>▪ Alert Notification Profile (ANP)</li> </ul>
1464_002	Added application callback for IRK generation and default generation callback.
1464_003	Added Storage mechanism (app_easy_storage) with optional secure features.
1464_004	Added SUOTA secure features.
1464_005	Added Secure Boot features <ul style="list-style-type: none"> <li>▪ Introduced Secure Secondary Bootloader for signed and/or encrypted images with multiple key support.</li> <li>▪ Added sign and encrypt image support to the mkimage executable/project.</li> </ul>
1464_006	Replaced Assembly start-up files with C files.
1464_007	Added flash programmer support for securely writing AES keys into OTP key storage.
1464_008	Upgraded IAR tool version to 9.60.3
1464_009	Added one-wire WIFI coexistence enabled via CFG_ONE_WIRE_COEX.
1464_010	Added support for multiple connections in the app files.
1464_011	Added support for additional OTP calibration values for RC32M and KDCO. Added prod_test command for RC32M and KDCO recalibration (only for DA14531).
1464_012	Added configurable UART baud rate for HCI project via binary editing.
1464_013	Added flash power down in prox_reporter project after boot.

### 5.3 Fixes and Improvements since 6.0.22.1401

Table 3. 6.0.24.1464 fixes and improvements

Fix number	Description
1464/01	Multiple fixes in ble_app_lecb project application and profile.
1464/02	Fixed Hardfault when using DCDC ROM functions and USE_POWER_MODE_BYPASS enabled.
1464/03	Changed value CFG_CALIBRATION_TEMP_DIFF to 5 when CFG_RF_LDO_CALIBRATION enabled.
1464/04	Fixed e <sup>2</sup> studio project indexing issues (compatible with e <sup>2</sup> studio 2025-04).
1464/05	Updated the set_recommended_settings() function for DA14535/DA14533.
1464/06	Fixed a PWM example bug for DA14531.
1464/07	Fixed UART corner case with pending interrupt while disabling interface.

Fix number	Description
1464/08	Fixed compilation errors when CFG_WLCSP_PACKAGE is defined.
1464/09	Fixed an issue where ANCS client app would not store bonding data in external flash (DA1453x).
1464/010	Fixed an issue where driver configuration structures were not compatible with ROM functions when building with LLVM (e <sup>2</sup> studio).
1464/011	Fixes in the heap area definitions in the IAR prox_reporter project.

## 5.4 Known Limitations of 6.0.24.1464

An active list of known limitations is maintained online:

[http://lpccs-docs.renesas.com/sdk6\\_kll/index.html](http://lpccs-docs.renesas.com/sdk6_kll/index.html)

## 6. Release History

### 6.1 Version 6.0.22.1401

Version 6.0.22.1401 of SDK 6 is released on Mar 14, 2024.

#### 6.1.1 Overview

This was a GA release of SDK6 which added support for DA14533, DA14535, DA14531-0x and DA14585/6 devices. This release can be used for application development.

#### 6.1.2 New and Updated Features of 6.0.22.1401

Table 4. 6.0.22.1401 new features

Feature number	Description
1401_001	Added experimental support for new device DA14533.
1401_002	Added support for Support DA1458x and DA1453x devices on e2studio.
1401_003	Added support for LLVM toolchain on e2studio.
1401_004	Extended GTL command set to improve the network co-processor use case.
1401_005	Added support for profiles Pulse Oximetry Service Server Role (PLXS) and Continuous Glucose Monitoring Service Server Role (CGMS)

#### 6.1.3 Fixes and Improvements since 6.0.20.1338

Table 5. 6.0.22.1401 fixes and improvements

Fix number	Description
1401/01	DA14535: Fixed bug where some SDK projects examples didn't include the DA14535 as a target device in application DISS configuration.
1401/02	Improved extended properties Reliable Write feature handling in Bond Management Control Point (BMSS).
1401/03	Fixed bug in find_common.h where Find Me Profile guarded by Glucose Profile defines.
1401/04	Removed 9-bits width support from spi_set_bitmode() function comment.
1401/05	DA14585/586: Updated DMA drives for PDM support.
1401/06	Fixed missing IAR Configurations to be able to set a breakpoint.
1401/07	DA14531-01: Fixed wrong delay in shifter settling in adc_input_shift_config() function.
1401/08	Fixed to output the BLE_EIP signal on all diagnostic capable pins.
1401/09	DA14535: Added missing parameters to XTAL32M dynamic trimming algorithm.
1401/10	Fixed CFG_NVDS_TAG_BLE_CA_MIN_RSSI default value that prevented Channel Map Update process to take place.
1401/11	Replaced bitwise AND used in i2c_get_mode() with logical AND.
1401/12	DA14535: Fixed RSSI data value in gapm_adv_report_ind which was incorrectly always 0.
1401/13	DA14531-01: Fixed crash with hardfault when Skip Slave Latency was used.
1401/14	DA14585/586: Fixed missing events when RCX is used and CFG_HIGH_TEMPERATURE is set.
1401/15	DA14535: Improved handling of LDO trim value in arch_system_init_vdd_clamp_for_rcx().
1401/16	DA14535: Added the updated CORE_AMP_REG_NULLBIAS value to the existing configuration of the XTAL32M_CTRL0_REG register in system_init().
1401/17	Fixed Timer1 Capture mode with LP clock.
1401/18	Improved user_config folder view in Keil projects.
1401/19	Disabled bonding for HTP periodic temperature measurements test case.
1401/20	DA14531-01: Fixed structure Ilm_le_env_tag which was different between SDK and the Stack.
1401/21	DA1453x: Optimized Secondary bootloader for large image files.
1401/22	Fixed and updated the uart2spi bridge project.
1401/23	DA14535: Fixed LDO_RET_TRIM value for 105C
1401/24	DA1453x (modules): Fixed FLASH writing delay during SUOTA operation

Fix number	Description
1401/25	DA14531-0x: Fixed LE TX in Production Test. While having a predefined set of packets set by the user the test did not stop.
1401/26	Fixed UART pin configuration editing through the bin file
1401/27	Fixed Unmached left curly bracket in user_app_callbacks when BLE_APP_SEC is zero.
1401/28	DA1453xMOD: Optimized flash unprotect delay
1401/29	Improved behavior of secondary bootloader for encrypted images
1401/30	DA14531 and DA14585:Fixed wrong limits for BLE_EIP
1401/31	Fixed profile code of WSS profile
1401/32	Fixed previous minor limitation in GLPS profile
1401/33	Fixed previous Hardfault in lld_sleep_compensate_func when CFG_DEVELOPMENT_DEBUG macro is defined

### 6.1.4 Known Issues of 6.0.22.1401

An active list of known limitations is maintained online:

[http://lpccs-docs.renesas.com/sdk6\\_kll/index.html](http://lpccs-docs.renesas.com/sdk6_kll/index.html)

## 6.2 Version 6.0.20.1338

Version 6.0.20.1338 of SDK 6 is released on Aug 11, 2023.

### 6.2.1 Overview

This was a GA release of SDK6 which added support for DA14533, DA14535, DA14531-0x and DA14585/6 devices. This release can be used for application development.

### 6.2.2 New and Updated Features of 6.0.20.1338

Table 6. 6.0.20.1338 new features

Feature number	Description
1338_001	Added support for new device DA14535.
1338_002	Added support for the skip slave latency feature.
1338_003	Added API for LE credit based channels.
1338_004	Added support for AT25XE512C, AT25DF512C, AT25XE011, AT25EU0011A, AT25XE021A, AT25FF081A, AT25DF011, AT25DN011, AT25XE041B, AT25FF041A, AT25SF041B, AT25XE081D SPI flash memories.
1338_005	Added SPI driver to support the GTL or HCI interface directly over the SPI bus.

### 6.2.3 Fixes and Improvements since 6.0.18.1182.1

Table 7. 6.0.20.1338 fixes and improvements

Fix number	Description
1338/01	Changed the default Bluetooth addresses of the BLE examples
1338/02	Changed the ADC driver to store and restore the initial offsets before and after an ADC measurement which may alter them.
1338/03	Fixed bug in HPTP profile. No indication was sent after reconnection.
1338/04	Disabled all interrupts when hibernation function is called. The interrupts disable is handled now by the respective hibernation function.
1338/05	DA14531-0x: Fixed OTP write using the prod_test.exe command line utility. Attempting to write more than one word was failing.
1338/06	Fixed UART issue that did not allow to empty all TX FIFO. The chip might go to sleep while they were unsent bytes in the FIFO.
1338/07	Fixed async I2C slave driver. It was not possible to receive 2 I2C frames consecutively.
1338/08	Improved static random Bluetooth address calculation formula.
1338/09	DA14531-0x: Fixed compilation issue in dbg_prod_output() function.
1338/10	DA14531-0x: Fixed prod_test f/w issue when configuring the device in continuous Tx with output power at 2.5 dbm. The TX power setting did not apply correctly.

Fix number	Description
1338/11	Always seed the used random number function generator with the random seed generated from the TRNG internal mechanism, which runs once after power cycle. The TRNG mechanism is now called before the BLE stack initialization function, which makes calls to the random number generator functions.
1338/12	DA14531-0x: Improved the XTAL32M configuration settings to make the XTAL32M circuitry more robust.
1338/13	Prevent UART from hanging when configuring the UART baud rate.
1338/14	DA14531-0x: Changed the ADC settling time as instructed by the h/w team.
1338/15	Handled on the application level the GATT service changed indication. A confirmation message was required to be sent back to BLE stack to prevent system hanging.
1338/16	Fixed returned error status in Custom profile. In case of an error the profile was always returning to the application a generic error code and not the specific one.
1338/17	DA14585/586: Fixed the following Bluetooth LE stack issue: SMP timeout timer was not started upon transmission of a Security Request command.
1338/18	Changed the library patch control mechanism per build. Now you can control at compile time which patches are going to be built in his/her application. Unused patches may be opted out at compile time to save more RAM for the application. For more details, please read documentation UM-B-119.
1338/19	Enabled LTO feature on GCC projects.
1338/20	Improved scatter file to enable unused RAM areas (gaps) to be used by the application.
1338/21	DA14531-0x: Enabled by default the extra RF calibration (RF LDO calibration), which fixes possible PER issues in the Rx path.
1338/22	DA14531-0x: Changed the preferred LDO_RET_TRIM value from '0xF' to '0xE'. A VDD undervoltage can occur when a HW_RST or a POR is asserted while the device is in sleep mode and LDO_RET_TRIM setting '0xF' is used. In some extreme cases (ppm level) this can cause a lockup of the device, only recoverable by a full power cycle. Setting LDO_RET_TRIM to '0xE' will prevent this from happening.

### 6.2.4 Known Issues of 6.0.20.1338

An active list of known limitations is maintained online:

[http://lpccs-docs.renesas.com/sdk6\\_kll/index.html](http://lpccs-docs.renesas.com/sdk6_kll/index.html)

## 6.3 Version 6.0.18.1182.1

Version 6.0.18.1182.1 of SDK 6 is released on Nov 25, 2022.

### 6.3.1 Overview

This is a GA release of SDK6 which added support for DA14533, DA14535, DA14531-0x and DA14585/6 devices. This release can be used for application development.

### 6.3.2 New and Updated Features of 6.0.18.1182.1

Table 8. 6.0.18.1182.1 new features

Feature number	Description
1182_001	Added support for DA14531-01 device which is a ROM variant of DA14531.

### 6.3.3 Fixes and Improvements since 6.0.16.1144

Table 9. 6.0.18.1182.1 fixes and improvements

Fix number	Description
1182/01	DA14531/585/586: Default C compiler change in Keil projects. All the released Keil projects are built with ARM v6 C compiler with LTO support enabled.
1182/02	DA14531/585/586: The default RAM retention mode changed. All the RAM cells are retained during extended sleep. You can still select which RAM cells can be retained during extended sleep. Because of the Default Retention mode change, the sleep current increases in some Bluetooth LE examples compared to the previous SDK6 releases.
1182/03	DA14531: Removed redundant 1144/06 patch from the DA14531 library files. The 1144/06 patch had been accidentally added to SDK 6.0.16 patches.



### 6.3.4 Known Issues of 6.0.18.1182.1

An active list of known limitations is maintained online:

[http://lpccs-docs.renesas.com/sdk6\\_kll/index.html](http://lpccs-docs.renesas.com/sdk6_kll/index.html)

## 6.4 Version 6.0.16.1144

Version 6.0.16.1144 of SDK 6 is released on Sep 28, 2021.

### 6.4.1 Overview

This was a GA release of SDK6 which added support for DA14533, DA14535, DA14531-0x and DA14585/6 devices. This release can be used for application development.

### 6.4.2 New and Updated Features of 6.0.16.1144

Table 10. 6.0.16.1144 new features

Feature number	Description
1143_001	Added support for the following SPI flash memories: AT25DF021A, AT25XE041D, AT25EU0021A.
1143_002	DA14531: The maximum external DC load current on the VBAT_HIGH rail during booting in boost mode is 50uA. As a result of this, an external SPI flash memory that is connected to VBAT_HIGH (when the DA14531 is working in boost mode) may not be operational for certain values of VBAT_LOW. This means that the DA14531 does not boot from the SPI flash memory. To overcome this limitation, a dedicated DA14531 pin is selected in the SPI flash driver to control the SPI flash powering up procedure.
1143_003	The SPI flash driver can disable by default the SPI flash memory protection (some SPI flash memories, such as the AT25DF021A, are memory protected after the power cycle), using a compile-time flag.
1143_004	DA14531: Added 1-wire UART support to the secondary bootloader.
1143_005	DA14531: Added the capability to enable/disable the UART or JTAG support in the secondary bootloader.

### 6.4.3 Fixes and Improvements since 6.0.14.1114

Table 11. 6.0.16.1144 fixes and improvements

Fix number	Description
1144/01	DA14531: Fixed issue with waking up from hibernation with no RAM retained. The device was overwriting the booter-applied values of the BANDGAP_REG, CLK_RC32M_REG, and CLK_RC32K_REG registers.
1144/02	DA14585/586: Fixed secondary bootloader issue with large images. During the run, the decryption of a large image might take longer than the default load value of the watchdog causing the watchdog timer to expire.
1144/03	DA14585/586: Fixed issue with XTAL16M trimmed devices, where the booter applied CLK_FREQ_TRIM_REG value was overwritten with zeros after device wake-up.
1144/04	Corrected the BMS Server. It was allowing delete operations without an authorization code to happen when an authorization code was required.
1144/05	Fixed: There is a possibility of using a Long Term Key (LTK) with all zeros in the Bluetooth subsystem if the Link Layer Encryption procedure occurs before the completion of the pairing procedure. This is fixed in the default app handler in SDK Bluetooth LE examples.
1144/06	Improved the stack behavior during the setting of data length (HCI_Set_Data_Length command) and Data Length Update procedure to improve interoperability.
1144/07	Fixed: On unexpected reception of Data Physical Channel PDU, the Bluetooth Controller stack terminate the connection using the Link Layer ACL Termination procedure instead of abandoning the connection as specified by the Link Layer part of Bluetooth core specification v5.2.

Fix number	Description
1144/08	DA14531: Fixed a rare occurrence of a race condition while accessing the exchange memory, which is shared between hardware and firmware, which can result in the loss of the LE ACL packet which was successfully received over the air.
1144/09	Additional checks are added in the Security Manager protocol (SMP) of the Bluetooth Host stack to detect reflected random values (Confirm value and Random value) during the LE legacy pairing procedure. On detection of the reflected public key, the pairing procedure fails. This improvement addresses the security vulnerability reported by the researchers in ANSSI regarding the "Authentication of the LE Legacy Pairing Protocol".
1144/10	While operating as an LE slave (peripheral role), the Link Layer validates the fields in the received LL_CONNECT_IND / LL_CONNECT_REQ PDU. The connection is considered lost if the received PDU contains one or more fields that are specified as Reserved for Future Use (RFU). This improvement is in accordance with the Link Layer Part of Bluetooth core specification v5.2.

#### 6.4.4 Known Issues of 6.0.16.1144

An active list of known limitations is maintained online:

[http://lpcps-docs.renesas.com/sdk6\\_kll/index.html](http://lpcps-docs.renesas.com/sdk6_kll/index.html)

### 6.5 Version 6.0.14.1114

Version 6.0.14.1144 of SDK 6 is released on Apr 29, 2020.

#### 6.5.1 Overview

This was a GA release of SDK6 that runs on the DA14531 and DA14585/6 devices. This release can be used for application development.

#### 6.5.2 New and Updated Features of 6.0.14.1114

Table 12. 6.0.14.1114 new features

Feature number	Description
1114_001	Whitelist support in a peripheral role. This feature provides limited functionality on Link Layer privacy by enabling the application to add devices to the whitelist while operating in the Peripheral role. It facilitates the device to allow connection only from the peer (remote) device that is listed in the whitelist. The feature works when the peer (remote) device uses a Public device address or Static Random device address or Resolvable Private device address. The number of devices that can be added to the whitelist depends upon the chipset used.
1114_002	DA14531: Adapt VDD clamp level in hibernation mode based on static temperature range selection.
1114_003	IAR v8.40.2 support (prox_reporter).
1114_004	WiFi coexistence support.
1114_005	DA14531: State-aware hibernation.

#### 6.5.3 Fixes and Improvements since 6.0.12.1020.2

Table 13. 6.0.14.1114 fixes and improvements

Fix number	Description
1114/01	Fixed known limitation 1020.05: (DA14531) The peripheral examples inside the SDK did not work in Boost mode due to the deactivation of the internal DCDC converter in the system initialization function.
1114/02	Defined extra free RAM area to be used by applications.
1114/03	DA14531: Improved ADC_VBAT command to read VBAT_LOW (prod_test).
1114/04	Added new HCI command to trigger h/w reset (prod_test).
1114/05	Added extra prod_test binaries per UART configuration.
1114/06	DA14531: Trigger TRNG mechanism every time RAM3 block was previously off.

Fix number	Description
1114/07	Fixed Issue: Incorrect handling on the reception of wrongly formed Security Manager Protocol PDU (packets that are less than what is expected for a specific opcode but with correct L2CAP length).
1114/08	Improvement: Incorrect SM_Pairing_Request is ignored without response. This behavior is as per the Bluetooth specification recommendation for handling invalid behavior of peer (remote) device.
1114/09	Fixed Issue (only for DA14585): Device instability when handling fragmented data packets is received from the peer (remote) device. If the start of the data packet received is fragmented within L2CAP & ATT header (i.e. 7 bytes), then corruption happens on heap memory.
1114/10	Swapped RTS/CTS signals in external processor projects.
1114/11	Passed connection index to application in custom profile write handler.
1114/12	Fixed write request in custom profile when RI is enabled.
1114/13	DA14531: Added support for ADC differential mode through existing ADC configuration structure.
1114/14	DA14531: Restored booter applied register values after hibernation wake-up.
1114/15	Fixed known issue 1020.01 (DA14531). The Transmit Power Level characteristic represents the current radiated transmit power level in dBm for the specified Bluetooth connection. This is as per the TX Power Service Specification.
1114/16	Fixed UART peripheral example to not get stuck in loopback mode.
1114/17	DA14531: Pointer arp_table placed in the retention memory area.
1114/18	DA14531: Changed the order of the ADC registers being restored in conditionally_run_radio_cals().
1114/19	DA14531: Disabled certain ROM SDK functions (SDK functions which have been placed in ROM) which may lead to s/w breakpoint.
1114/20	Added function callback to handle line status errors in the UART driver.
1114/21	Enabled by default the DMA support when booting from SPI flash memory (secondary bootloader).
1114/22	Added support to alter the default pairing response message.
1114/23	Moved range extender initialization function call before GPIO initialization.
1114/24	Handled properly the I2C_INT_TX_ABORT interrupt when a read operation is performed in DMA mode.
1114/25	Fixed known limitation 1020.02 (DA14585/586/531): In external processor configuration the GPIO used for waking up is not programmed immediately after UART flow off. This may lead to missing communication over UART with the external processor if the external processor tries to wake up the device too soon.
1114/26	Improved RSSI calculation formula.
1114/27	Handled properly the ATT_Handle_Value_Indication by the GATT Client. The device responds with ATT_HANDLE_VALUE_CFM for the ATT_HANDLE_VALUE_IND received for Characteristics where Client Changed Characteristics is NOT configured for Indication. This change in behavior is as per Generic Attribute Profile (GATT) specification and improves the interoperability with some Android-based phones running Android OS P & Q.
1114/28	DA14531: Used properly the transparent light sleep (TLS) mode of the RAM cells.
1114/29	Fixed inconsistent behavior when trying to start a new ADV event while a previous one is already started.
1114/30	Fixed known issue (DA14531) 1020.04_ DA14531: when _EXCLUDE_ROM_PRF_ is not defined and no BLE profiles are used in the application context, BLE_NB_USED_PROFILES must be set to 0. If not, the first four addresses of the executable – initial Stack Pointer, Reset Handler, NMI Handler, and HardFault Handler – is overwritten with zeros. Affected SDK projects: hci; ble_app_noncon; prod_test.
1114/31	DA14531: Fixed OTP header layout used by SmartSnippets Studio.
1114/32	DA14531: Added support for OTP write command.
1114/33	Added support for P25Q11U SPI flash memory.
1114/34	DA14531: Added support for 1-wire UART to prod_test.exe utility.
1114/35	DA14531: Corrected temperature coefficient value in ADC driver.

Fix number	Description
1114/36	DA14531: Modified flash programmer (UART version) scatter file.
1114/37	Fixed toolchain version used by SmartSnippets Studio (instead of being "7-2018-q2" was "7-2018q2").
1114/38	<p>DA14585: The processing of LL_CHANNEL_MAP_IND PDU after the Connection Event Counter is specified as an Instant field in the PDU does not lead to the termination of the connection. This change improves the behavior of the stack if the peer device (master) erroneously performs the Link Layer Channel Map Update procedure while the Link Layer Connection Parameters Request procedure is ongoing by processing the LL_CHANNEL_MAP_IND PDU after the Connection Parameters Request procedure is completed. This change in behavior may result in keeping the connection alive during this out-of-specification behavior of the smartphone.</p> <p>Prior to this change, the processing of such LL_CHANNEL_MAP_IND would result in the termination of the connection. This change in DA14585 aligns with DA14531 behavior in the handling of LL_CHANNEL_MAP_IND PDU received during an ongoing Connection Parameters Request procedure.</p>

#### 6.5.4 Known Issues of 6.0.14.1114

Table 14. 6.0.14.1114 known issues

Issue Number	Description
933.04	DA14585/586/531: Default system rand() function is not true random (not NIST compliant). It is suggested to use the alternative chacha20() function when true random numbers are required (NIST compliant).
722.08	DA14585/586: HCI ACL fragmentation does not work correctly.

### 6.6 Version 6.0.12.1020.2

Version 6.0.12.1020.2 was released on Dec 9, 2019.

#### 6.6.1 Overview

This was the second GA release of SDK6 that runs on the DA14531 devices. It also supported DA14585/6 devices. This release can be used for application development.

#### 6.6.2 Fixes and Improvements since 6.0.12.1020

Table 15. 6.0.12.1020.2 fixes and improvements

Fix number	Description
1020.02.01	DA14531: Updated calibration for improved radio functionality in applications with fast temperature swings

#### 6.6.3 Known Issues of 6.0.12.1020.2

Table 16. 6.0.12.1020.2 known issues

Issue number	Description
1020.01	DA14531: Wrong TX power level value is returned by TX Power GATT service. The returned value is the setting of the register, not the dBm. Furthermore, the returned value refers to the advertising power, even if the connection power is different.
1020.02	DA14585/586/531: In external processor configuration the GPIO used for waking up is not programmed immediately after UART flow off. This may lead to missing communication over UART with the external processor if the external processor tries to wake up the device too soon.
1020.03	The prod_test.hex file might have memory alignment issues preventing its usage In SmartSnippets Toolbox RF Master or with Bluetooth tester equipment. The corresponding prod_test.bin files should be used instead.
1020.04	DA14531: when <code>_EXCLUDE_ROM_PRF</code> is not defined and no Bluetooth LE profiles are used in the application context, <code>BLE_NB_USED_PROFILES</code> must be set to 0. If not, the first four addresses of the executable – initial Stack Pointer, Reset Handler, NMI Handler, and

Issue number	Description
	HardFault Handler – is overwritten with zeros. Affected SDK projects: hci; ble_app_noncon; prod_test.
933.04	DA14585/586/531: Default system rand() function is not true random (not NIST compliant). It is suggested to use the alternative chacha20() function when true random numbers are required (NIST compliant).

#### 6.6.4 Known Limitations of 6.0.12.1020.2

Table 17. 6.0.12.1020.2 known limitations

Issue Number	Description
1020.05	DA14531: The peripheral examples inside the SDK do not work in Boost mode due to the deactivation of the internal DCDC converter in the system initialization function.

### 6.7 Version 6.0.12.1020

Version 6.0.12.1020 of SDK6 was released on Oct 31, 2019.

#### 6.7.1 Overview

This was the first GA release of SDK6 that runs on the DA14531 devices. It also supported DA14585/6 devices. This release can be used for application development.

#### 6.7.2 New and Updated Features of 6.0.12.1020

Table 18. 6.0.12.1020 features

Feature number	Description
1020/001	Supports DA14531, DA14585 and DA14586 devices.
1020/002	Includes Eclipse/GCC project example (prox_reporter).
1020/003	Supported by SmartSnippets tools version 2.0.10.
1020/004	Doxygen documentation of all API functions.
1020/011	Updated 531 radio driver.
1020/012	RF driver for DA14531.
1020/013	DA14531: API function to dynamically control radio TX power.
1020/014	DA14531: RF power control -20 ...3 dBm.
1020/015	SPI driver for DA14531 (master/slave buffered and DMA driven transactions).
1020/016	I2C driver for DA14585/586/531.
1020/017	RTC driver for DA14531.
1020/018	OTP driver for DA14531.
1020/019	Support for OTP configuration script in 531.
1020/020	Support for DA14531 ROM functions.
1020/021	Near field mode API for DA14531.
1020/022	API function to enable/disable the Hardware Reset pin in DA14531.
1020/023	DA14531 support in Wakeup and Quadrature Decoder driver.
1020/024	DA14531 support in GPIO driver.
1020/025	Added DA14531 target in the project: ble_app_peripheral.
1020/026	Added DA14531 target in the project: ble_app_profile.
1020/027	Added DA14531 target in the project: ble_app_barebone.
1020/028	Added DA14531 target in the project: prox_monitor_ext.
1020/029	Added DA14531 target in the project: hci.
1020/030	Peripheral examples ported to DA14531.
1020/031	Batt_lvi peripheral example project DA14531.
1020/032	DA14531: Support for 1-wire UART (driver and flash programmer).
1020/033	Temperature sensor driver.

Feature number	Description
1020/034	Readout of internal temperature.
1020/035	AES driver (data and link).
1020/036	DCDC converter API to control VBAT_H for OTP and GPIOs in Boost mode.
1020/037	Use of temperature sensor to trigger RF calibration during run-time.
1020/038	Secondary bootloader project.
1020/039	Proximity reporter example.
1020/040	Prox_reporter application wakeup using RTC or Timer 1 (apart from GPIO).
1020/041	Template example.
1020/042	Prod_Test firmware.
1020/043	OTA example project.
1020/044	Security example.
1020/045	Sleep Example.
1020/046	Add support for Shipping (Hibernation) mode.
1020/047	ADC Driver with DMA support.
1020/048	RCX-only operation - no need for XTAL32K.
1020/049	Added extra power optimization method using the XTAL16M adaptive settling time algorithm. It is enabled by default and can offer power savings of up to 10% for a 10-ms connection interval.
1020/050	Used the default XTAL16M trim value when the XTAL16M is uncalibrated.
1020/051	POR on Vbat high/low Voltage Monitor.
1020/052	Deep sleep support.
1020/053	Timer1/2 support.
1020/054	Disabled DC-DC auto calibration (Buck and Boost mode).
1020/055	Added 38K4 baud rate support in production test f/w.
1020/056	Added support for Boost mode.
1020/057	Added API for AES-CCM, AES-CBC, and AES-CMAC operations.
1020/101	Compliant with BLE 5.0 (DA14585/6) and BLE 5.1 (DA14531) Core specifications.
1020/102	Data Packet Length Extension.
1020/103	Enhanced Privacy 1.2.
1020/104	Efficient non-connectable advertising.
1020/105	Added API to support controller privacy (peripheral role).
1020/106	BLE LE Secure Connections.
1020/107	Function for the unique static random BD address generation using OTP header values.
1020/108	Adds a key renewal command that can be called after a number of failed pairing attempts
1020/109	Added support to disable the ROM ECC key generation calculations if the Secure Connections feature is not used.
1020/110	Added support for URI advertising data type.
1020/111	Added support for the GATT service layer changed the characteristic of the application layer.

### 6.7.3 Known Issues of 6.0.12.1020

Table 19. 6.0.12.1020 known Issues

Issue number	Description
1020.01	DA14531: Wrong TX power level value is returned by TX Power GATT service. The returned value is the setting of the register, not the dBm. Furthermore, the returned value refers to the advertising power, even if the connection power is different.
1020.02	DA14585/586/531: In external processor configuration the GPIO used for waking up is not programmed immediately after UART flow off. This may lead to missing communication over UART with the external processor if the external processor tries to wake up the device too soon.

Issue number	Description
1020.03	The prod_test.hex file might have memory alignment issues preventing its usage In SmartSnippets Toolbox RF Master or with Bluetooth tester equipment. The corresponding prod_test.bin files should be used instead.
1020.04	DA14531: when <code>_EXCLUDE_ROM_PRF_</code> is not defined and no Bluetooth LE profiles are used in the application context, <code>BLE_NB_USED_PROFILES</code> must be set to 0. If not, the first four addresses of the executable – initial Stack Pointer, Reset Handler, NMI Handler, and HardFault Handler – is overwritten with zeros. Affected SDK projects: hci; ble_app_noncon; prod_test.
933.04	DA14585/586/531: Default system rand() function is not true random (not NIST compliant). It is suggested to use the alternative chacha20() function when true random numbers are required (NIST compliant).

#### 6.7.4 Known Limitations of 6.0.12.1020

Table 20. 6.0.12.1020 known limitations

Issue number	Description
1020.05	DA14531: The peripheral examples inside the SDK do not work in boost mode due to the deactivation of the internal DCDC converter in the system initialization function.



## Appendix A Software Versioning Rules

This describes the software version numbers and does not apply to documentation version numbers (as found in the footer of this document).

Each software version number string consists of four numbers: MAJOR. BRANCH. MINOR. and BUILD.

#MAJOR: It is increased (by one only) if the project undergoes a major modification, for example major ROM changes. It usually changes only when the project sources undergo major restructuring affecting most of the repository. It is initialized at 1.

#BRANCH: Used in the case of concurrent projects that for special reasons need to be spun off the major repository. It corresponds to different versions of the repository code that have to be supported concurrently. In this case each branch number corresponds to a different GIT branch. The basic project has BRANCH id 0.

#MINOR: Odd numbers indicate Engineering (or Patch or Binary) versions, even numbers indicate Full release versions or Release Candidates of Full versions. Each Full release increases this number by one. After the Full release, the number is increased by one again. Therefore, Project releases correspond to release numbers like 2.0.1.xxx, 2.0.2.xxx. etc. The #MINOR number is initialized at 1.

#BUILD: The # BUILD number increases by one at every repository update and thus indicates the total number of changes since repository initialization. The BUILD number is initialized at 1.



## 7. Document Revision History

This section summarizes the changes made to this document and not to the software that this document describes.

Revision	Date	Description
1.7	May 8, 2025	Converted into Renesas template. Release including fixes and improvements.
1.6	Mar 15, 2024	Updates to software version 6.0.22.1401.
1.5	Sep 21, 2023	Updates to software version 6.0.20.1338.
1.4	Nov 25, 2022	Updates to software version 6.0.18.1182.1.
1.3	Sep 28, 2021	Updates to software version 6.0.16.1144.
1.2	Apr 29, 2020	Updates to software version 6.0.14.1114.
1.1	Dec 9, 2019	Updates to software version 6.0.12.1020.2.
1.0	Oct 31, 2019	The first release. Software version 6.0.12.1020.

## Status Definitions

Status	Definition
DRAFT	The content of this document is under review and subject to formal approval, which may result in modifications or additions.
APPROVED or unmarked	The content of this document has been approved for publication.

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